

# Single Inverter

## NLV74HC1G04

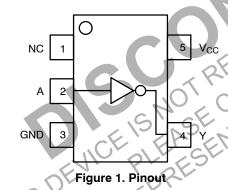
The NLV4HC1G04 is a high speed CMOS inverter fabricated with silicon gate CMOS technology.

The internal circuit is composed of multiple stages, including a buffer output which provides high noise immunity and stable output.

The NLV74HC1G04 output drive current is 1/2 compared to NLV74HC series.

#### **Features**

- High Speed:  $t_{PD} = 7 \text{ ns (Typ)}$  at  $V_{CC} = 5 \text{ V}$
- Low Power Dissipation:  $I_{CC} = 1 \mu A \text{ (Max)}$  at  $T_A = 25^{\circ}\text{C}$
- High Noise Immunity
- Balanced Propagation Delays  $(t_{pLH} = t_{pHL})$
- Symmetrical Output Impedance ( $I_{OH} = I_{OL} = 2 \text{ mA}$ )
- Chip Complexity: < 100 FETs
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant



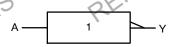


Figure 2. Logic Symbol

PIN ASSIGNMENT					
1	NC				
2	А				
3	GND				
4	Υ				
5	V <sub>CC</sub>				



SC-88A DF SUFFIX CASE 419A



**MARKING** 



TSOP-5 DT SUFFIX CASE 483



XX = Device Code M = Date Code\*

■ = Pb-Free Package

(Note: Microdot may be in either location)
\*Date Code orientation and/or position may vary
depending upon manufacturing location.

#### **FUNCTION TABLE**

Input A	Output Y
BOTMA	Н
O H	L

#### **ORDERING INFORMATION**

See detailed ordering, marking and shipping information in the package dimensions section on page 5 of this data sheet.

#### **MAXIMUM RATINGS**

Symbol	Parameter	Value	Unit
V <sub>CC</sub>	DC Supply Voltage	-0.5 to +7.0	V
V <sub>IN</sub>	DC Input Voltage	-0.5 to V <sub>CC</sub> +0.5	V
V <sub>OUT</sub>	DC Output Voltage	-0.5 to V <sub>CC</sub> +0.5	V
I <sub>IK</sub>	DC Input Diode Current	±20	mA
I <sub>OK</sub>	DC Output Diode Current	±20	mA
I <sub>OUT</sub>	DC Output Source/Sink Current	±12.5	mA
I <sub>CC</sub> or I <sub>GND</sub>	DC Supply Current per Supply Pin or Ground Pin	±25	mA
T <sub>STG</sub>	Storage Temperature Range	-65 to +150	°C
TL	Lead Temperature, 1 mm from Case for 10 Seconds	260	°C
$T_J$	Junction Temperature Under Bias	+150	°C
$\theta_{JA}$	Thermal Resistance (Note 1) SC-88/TSOP-		°C/W
P <sub>D</sub>	Power Dissipation in Still Air at 85°C SC–88/TSOP-		mW
MSL	Moisture Sensitivity	Level 1	
F <sub>R</sub>	Flammability Rating Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
V <sub>ESD</sub>	ESD Withstand Voltage (Note 2)  Human Body Mode Charged Device Mode		V
I <sub>LATCHUP</sub>	Latchup Performance (Note 3)	±500	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality

- should not be assumed, damage may occur and reliability may be affected.

  1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 20 ounce copper trace with no air flow per JESD51-7.

  2. HBM tested to ANSI/ESDA/JEDEC JS-001-2017. CDM tested to JESD22-C101-F. JEDEC recommends that ESD qualification to EIA/JESD22-A115A (Machine Model) be discontinued per JEDEC/JEP172A.

3. Tested to EIA/JESD78 Class II.

### RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V <sub>CC</sub>	DC Supply Voltage	2.0	6.0	V
V <sub>IN</sub>	DC Input Voltage		V <sub>CC</sub>	V
V <sub>OUT</sub>	DC Output Voltage		V <sub>CC</sub>	V
T <sub>A</sub>	Operating Temperature Range	-55	+125	°C
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time $\begin{array}{c} V_{CC}=2.0\ V\\ V_{CC}=3.0\ V\\ V_{CC}=4.5\ V\\ V_{CC}=6.0\ V \end{array}$	0 0 0 0	1000 600 500 400	ns

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

#### DC ELECTRICAL CHARACTERISTICS

			V <sub>CC</sub>	Т	A = 25°	С	-40°C ≤ 1	Γ <sub>A</sub> ≤ 85°C	-55°C ≤ T	<sub>A</sub> ≤ 125°C	
Symbol	Parameter	Test Conditions	(V)	Min	Тур	Max	Min	Max	Min	Max	Unit
V <sub>IH</sub>	High-Level Input Voltage		2.0 3.0 4.5 6.0	1.5 2.1 3.15 4.20	- - -		1.5 2.1 3.15 4.20	- - -	1.5 2.1 3.15 4.20	- - -	V
V <sub>IL</sub>	Low-Level Input Voltage		2.0 3.0 4.5 6.0	- - -	- - -	0.5 0.9 1.35 1.80	- - - -	0.5 0.9 1.35 1.80	- - - -	0.5 0.9 1.35 1.80	V
V <sub>OH</sub>	High-Level Output Voltage	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OH} = -20 \mu A$	2.0 3.0 4.5 6.0	1.9 2.9 4.4 5.9	2.0 3.0 4.5 6.0		1.9 2.9 4.4 5.9	- - -	1.9 2.9 4.4 5.9	- - -	٧
		$V_{IN} = V_{IH}$ or $V_{IL}$ $I_{OH} = -2$ mA $I_{OH} = -2.6$ mA	4.5 6.0	4.18 5.68	4.31 5.80	-	4.13 5.63	-	4.08 5.58	M <sub>D</sub> .	
V <sub>OL</sub>	Low-Level Output Voltage	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OL} = 20 \mu A$	2.0 3.0 4.5 6.0	- - -	0.0 0.0 0.0 0.0	0.1 0.1 0.1 0.1	-	0.1 0.1 0.1 0.1	NDE	0.1 0.1 0.1 0.1	٧
		$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OL} = 2 \text{ mA}$ $I_{OL} = 2.6 \text{ mA}$	4.5 6.0	-	0.17 0.18	0.26 0.26	)-\	0.33 0.33	-	0.40 0.40	
I <sub>IN</sub>	Input Leakage Current	V <sub>IN</sub> = 6.0 V or GND	6.0		-	± 0.1	: O-Y	±1.0	10/2	±1.0	μΑ
I <sub>CC</sub>	Quiescent Supply Current	V <sub>IN</sub> = V <sub>CC</sub> or GND	6.0			4.0	IRO	219	-	40	μΑ

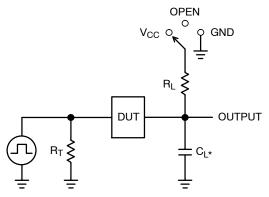
Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

## AC ELECTRICAL CHARACTERISTICS

	46		T	<sub>A</sub> = 25°	ó	-40°C ≤ 1	Γ <sub>A</sub> ≤ 85°C	-55°C ≤ T	<sub>A</sub> ≤ 125°C	
Symbol	Parameter	Test Conditions	Min	Тур	Max	Min	Max	Min	Max	Unit
t <sub>PLH</sub> ,	Propagation Delay,	$V_{CC} = 5.0 \text{ V}  C_L = 15 \text{ pF}$	//-	3.5	15	-	20	-	25	ns
t <sub>PHL</sub>	A to Y	$V_{CC} = 2.0 \text{ V}$ $C_{L} = 50 \text{ pF}$ $V_{CC} = 3.0 \text{ V}$	-	20	100	-	125	-	155	
		$V_{CG} = 3.0 \text{ V}$	-	11	27	_	35	_	90	
		V <sub>CC</sub> = 4.5 V	-	8	20	_	25	_	35	
		$V_{CC} = 6.0 \text{ V}$	_	7	17	_	21	_	26	
t <sub>TLH</sub> ,	Output Transition	$V_{CC} = 5.0 \text{ V}$ $C_L = 15 \text{ pF}$	-	3	10	-	15	-	20	ns
t <sub>THL</sub>	Time	$V_{CC} = 2.0 \text{ V}$ $C_L = 50 \text{ pF}$	_	25	125	_	155	_	200	
	*	V <sub>CC</sub> = 3.0 V	-	16	35	_	45	_	60	
		$V_{CC} = 4.5 \text{ V}$	_	11	25	_	31	_	38	
		V <sub>CC</sub> = 6.0 V	-	9	21	-	26	-	32	
C <sub>IN</sub>	Input Capacitance		_	5	10	_	10	_	10	pF

		Typical @ 25°C, V <sub>CC</sub> = 5.0 V	
$C_{PD}$	Power Dissipation Capacitance (Note 4)	10	pF

<sup>4.</sup> C<sub>PD</sub> is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I<sub>CC(OPR)</sub> = C<sub>PD</sub> • V<sub>CC</sub> • f<sub>in</sub> + I<sub>CC</sub>. C<sub>PD</sub> is used to determine the no–load dynamic power consumption; P<sub>D</sub> = C<sub>PD</sub> • V<sub>CC</sub><sup>2</sup> • f<sub>in</sub> + I<sub>CC</sub> • V<sub>CC</sub>.



Test	Switch Position	C <sub>L</sub> , pF	R <sub>L</sub> , Ω
t <sub>PLH</sub> / t <sub>PHL</sub>	Open		Х
t <sub>TLH</sub> / t <sub>THL</sub> (Note 5)	Open	See AC Characteristics Table	Х
t <sub>PLZ</sub> / t <sub>PZL</sub>	V <sub>CC</sub>	Table	1 k
t <sub>PHZ</sub> / t <sub>PZH</sub>	GND		1 k

X - Don't Care

\* $C_L$  includes probe and jig capacitance  $R_T$  is  $Z_{OUT}$  of pulse generator (typically 50 W) f = 1 MHz

Figure 3. Test Circuit

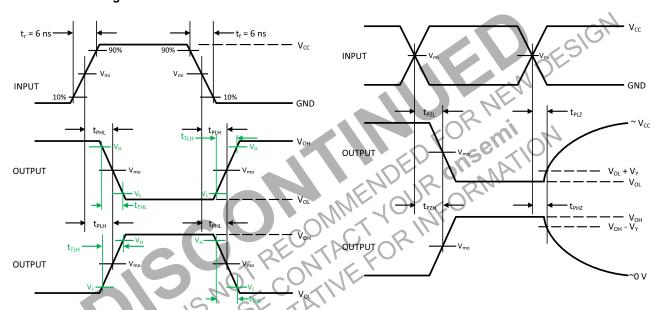


Figure 4. Switching Waveforms

	115		V <sub>mo</sub> , V			
V <sub>CC</sub> , V	V <sub>mi</sub> , V	t <sub>PLH</sub> , t <sub>PHL</sub>	$t_{PZL}, t_{PLZ}, t_{PZH}, t_{PHZ}$	$V_L, V$	V <sub>H</sub> , V	$V_Y$ , $V$
3.0 to 3.6	V <sub>CC</sub> /2	V <sub>CC</sub> /2	V <sub>CC</sub> /2	V <sub>OL</sub> + 0.1 (V <sub>OH</sub> – V <sub>OL</sub> )	V <sub>OL</sub> + 0.9 (V <sub>OH</sub> – V <sub>OL</sub> )	0.3
4.5 to 5.5	V <sub>CC</sub> /2	V <sub>CC</sub> /2	V <sub>CC</sub> /2	V <sub>OL</sub> + 0.1 (V <sub>OH</sub> – V <sub>OL</sub> )	V <sub>OL</sub> + 0.9 (V <sub>OH</sub> – V <sub>OL</sub> )	0.3

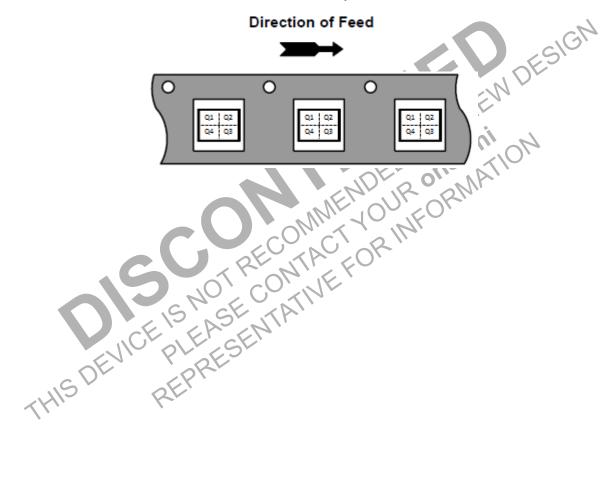
<sup>5.</sup>  $t_{TLH}$  and  $t_{THL}$  are measured from 10% to 90% of ( $V_{OH}$  –  $V_{OL}$ ), and 90% to 10% of ( $V_{OH}$  –  $V_{OL}$ ), respectively.

#### **ORDERING INFORMATION**

Device	Packages	Specific Device Code	Pin 1 Orientation (See below)	Shipping <sup>†</sup>
MC74HC1G04DFT1G-L22038	SC-88A	H5	Q2	3000 / Tape & Reel
NLVHC1G04DFT1G*	SC-88A	H5	Q2	3000 / Tape & Reel
MC74HC1G04DFT2G-L22038	SC-88A	H5	Q4	3000 / Tape & Reel
NLVHC1G04DFT2G*	SC-88A	H5	Q4	3000 / Tape & Reel
MC74HC1G04DTT1G	TSOP-5	H5	Q4	3000 / Tape & Reel

<sup>†</sup>For complete information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Pin 1 Orientation in Tape and Reel



<sup>\*</sup>NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.





#### SC-88A (SC-70-5/SOT-353) CASE 419A-02 ISSUE M

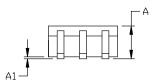
**DATE 11 APR 2023** 

#### NOTES:

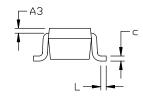
- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. 419A-01 DBSOLETE, NEW STANDARD 419A-02
- 4. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH,
  PROTRUSIONS, OR GATE BURRS.MOLD FLASH, PROTRUSIONS,
  OR GATE BURRS SHALL NOT EXCEED 0.1016MM PER SIDE.

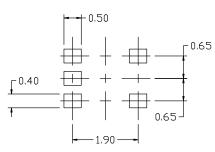
DIM	MI	MILLIMETERS				
ואונת	MIN.	N□M.	MAX.			
А	0.80	0.95	1.10			
A1			0.10			
A3	0,20 REF					
b	0.10	0.20	0.30			
C	0.10		0.25			
D	1.80	2.00	2,20			
Е	2.00	2.10	2.20			
E1	1.15	1.25	1.35			
е	0.65 BSC					
L	0.10	0.15	0.30			

# 5 + E1 E1 -5X b



◆ 0.2 M B M





# RECOMMENDED MOUNTING FOOTPRINT

For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SDLDERRM/D.

#### GENERIC MARKING DIAGRAM\*



\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

XXX = Specific Device Code

M = Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

STYLE 1:
PIN 1. BASE
<ol><li>EMITTER</li></ol>
3. BASE
<ol><li>COLLECTOR</li></ol>
<ol><li>COLLECTOR</li></ol>

YLE 2	2:
IN 1.	ANODE
2.	EMITTER
3.	BASE
4.	COLLECTOR
5.	CATHODE

STYLE 3: PIN 1. ANODE 1 2. N/C 3. ANODE 2 4. CATHODE 2 5. CATHODE 1 STYLE 4: PIN 1. SOURCE 1 2. DRAIN 1/2 3. SOURCE 1 4. GATE 1 5. GATE 2

STYLE 5: PIN 1. CATHODE 2. COMMON ANODE 3. CATHODE 2 4. CATHODE 3 5. CATHODE 4

STYLE 6: PIN 1. EMITTER 2 2. BASE 2 3. EMITTER 1 4. COLLECTOR STYLE 7:
PIN 1. BASE
2. EMITTER
3. BASE
4. COLLECTOR
5. COLLECTOR

STYLE 8:
PIN 1. CATHODE
2. COLLECTOR
3. N/C
4. BASE
5. EMITTER

STYLE 9: PIN 1. ANODE 2. CATHODE 3. ANODE 4. ANODE 5. ANODE Note: Please refer to datasheet for style callout. If style type is not called out in the datasheet refer to the device datasheet pinout or pin assignment.

**DOCUMENT NUMBER:** 

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**DESCRIPTION:** 

5. COLLECTOR 2/BASE 1

SC-88A (SC-70-5/SOT-353)

PAGE 1 OF 1

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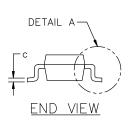


#### TSOP-5 3.00x1.50x0.95, 0.95P **CASE 483 ISSUE P**

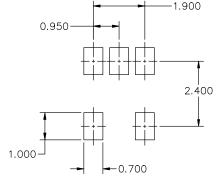
**DATE 01 APR 2024** 

#### NOTES:

- DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5-2018.
- ALL DIMENSION ARE IN MILLIMETERS (ANGLES IN DEGREES). MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. 3. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
- DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OF GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE. DIMENSION D.
- OPTIONAL CONSTRUCTION: AN ADDITIONAL TRIMMED LEAD IS ALLOWED IN THIS LOCATION. TRIMMED LEAD NOT TO EXTEND MORE THAN 0.2 FROM BODY.



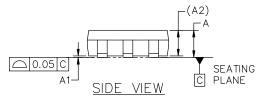
DIM	MILLIMETERS			
	MIN.	NOM.	MAX.	
Α	0.900	1.000	1.100	
A1	0.010	0.055	0.100	
A2	0.950 REF.			
b	0.250	0.375	0.500	
С	0.100	0.180	0.260	
D	2.850	3.000	3.150	
Е	2.500	2.750	3.000	
E1	1.350	1.500	1.650	
е	0.950 BSC			
L	0.200	0.400	0.600	
Θ	0.	5°	10°	

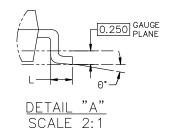


RECOMMENDED MOUNTING FOOTPRINT\*

FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

# NOTE 5 В Ė1 PIN 1 **IDENTIFIER** TOP VIEW





#### **GENERIC MARKING DIAGRAM\***





XXX = Specific Device Code

= Pb-Free Package

= Date Code

Analog Discrete/Logic

XXX = Specific Device Code

= Assembly Location = Year

W = Work Week

= Pb-Free Package

(Note: Microdot may be in either location)

М

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

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